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FORM PTC  
(Rev. 6-93)

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

FORM COVER SHEET  
PATENTS ONLY

Attorney Docket No.: 48370-0061

To the Commissioner for Patents **ATTN: MAIL STOP ASSIGNMENT RECORDATION SERVICES**  
Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):  
1) Kenji YANAGISAWA  
Additional names of conveying party(ies) attached?  
 Yes  No

2. Name and address of receiving party(ies):  
Name: SHINKO ELECTRIC INDUSTRIES CO., LTD.  
Address: 80, Oshimada-machi, Nagano-shi,  
Nagano, 381-2287, Japan


3. Nature of conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other \_\_\_\_\_  
Execution Date: November 16, 2007

Additional name(s) & address(es) attached?  
 Yes  No

4. New Application number(s) or patent number(s): **NEW APPLICATION**  
If this document is being filed together with a new application the execution date of the application is:  
November 16, 2007  
A. Patent Application No.(s) B. Patent No.(s)  
Additional numbers attached:  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:  
Name: John G. Smith  
Internal Address: DRINKER BIDDLE & REATH LLP  
Customer No. 55694  
Street Address: 1500 K. Street, NW., Suite 1100  
City: Washington State: D.C. Zip: 20005-1209

6. Total number of applications and patents involved: 1  
7. Total fee (37 C.F.R. §3.41): \$40.00  
 Enclosed  
 Authorized to be charged to Deposit Account 50-0573  
8. Deposit Account No. 50-0573  
(Attach duplicate page if paying by deposit account)

9. Statement and Signature  
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.  
John G. Smith, Reg. No. 33,818  
Name of Person Signing  
  
Signature  
November 27, 2007  
Date  
Total number of pages including cover sheet, attachments and documents: 2

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**ASSIGNMENT**

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:  
**MANUFACTURING METHOD OF OPTICAL-ELECTRICAL SUBSTRATE AND OPTICAL-ELECTRICAL SUBSTRATE**

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on \_\_\_\_\_, (Serial No. \_\_\_\_\_); and

WHEREAS, Shinko Electric Industries Co., Ltd., a corporation of Japan, whose post office address is 80, Oshimada-machi, Nagano-shi, Nagano, 381-2287, Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor Kenji YANAGISAWA	Assignor's Signature <i>Kenji Yanagisawa</i>	Date November 16, 2007
Address c/o Shinko Electric Industries Co., Ltd., 80, Oshimada-machi, Nagano-shi, Nagano, 381-2287, Japan		Citizenship Japan
Full Name of Second Assignor	Assignor's Signature	ate
Address		Citizenship
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		